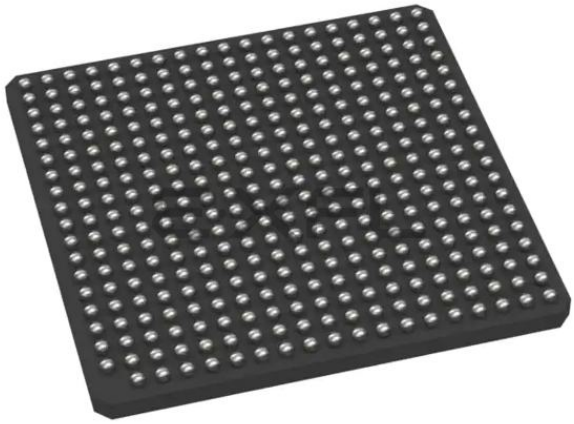

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Details	
Product Status	Last Time Buy
Core Processor	PowerPC G4
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	1.267GHz
Co-Processors/DSP	Multimedia; SIMD
RAM Controllers	-
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	1.5V, 1.8V, 2.5V
Operating Temperature	-40°C ~ 105°C (TA)
Security Features	-
Package / Case	360-BCBGA, FCCBGA
Supplier Device Package	360-FCCBGA (25x25)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc7448thx1267nd

Freescale Semiconductor
Technical Data

Document Number: MPC7448ECS02AD
Rev. 2, 04/2007

MPC7448 Hardware Specifications Addendum for the MC7448T*xxnnnnmx* Series

This document describes part-number-specific changes to recommended operating conditions and revised electrical specifications, as applicable, from those described in the general *MPC7448 RISC Microprocessor Hardware Specifications*. The MPC7448 is a PowerPC™ microprocessor built on Power Architecture™ technology.

Specifications provided in this document supersede those in the *MPC7448 RISC Microprocessor Hardware Specifications*, Rev. 3 or later, for the part numbers listed in Table A only. Specifications not addressed herein are unchanged. Because this document is frequently updated, refer to the website on the back page of this document or to your Freescale sales office for the latest version.

Note that headings and table numbers in this document are not consecutively numbered. They are intended to correspond to the heading or table affected in the general hardware specification.

Part numbers addressed in this document are listed in Table A.

Freescale Part Numbers Affected:

MC7448THX1000Nx
MC7448THX1267Nx
MC7448THX1400Nx
MC7448THX1700LD
PPC7448THX1000Nx
PPC7448THX1267Nx
PPC7448THX1400Nx

Table A. Part Numbers Addressed by This Data Sheet

Freescale Part Number	Operating Conditions			Significant Differences from Hardware Specifications
	CPU Frequency (MHz)	V_{DD}	T_j (•C)	
MC7448THX1000Nx	1000	1.0 V ± 50 mV	–40 to 105	Modified core frequency and voltage to reduce power consumption, extended operating temperature.
MC7448THX1267NC	1267	1.1 V ± 50 mV		
MC7448THX1267ND	1267	1.05 V ± 50 mV		
MC7448THX1400Nx	1400	1.15 V ± 50 mV [2]		
MC7448THX1700LD	1700	1.3 V +20/-50 mV		
PPC7448THX1000Nx [1]	1000	1.0 V ± 50 mV		
PPC7448THX1267NC[1]	1267	1.1 V ± 50 mV		
PPC7448THX1267ND[1]	1267	1.05 V ± 50 mV		
PPC7448THX1400Nx[1]	1400	1.15 V ± 50 mV [2]		

Note:
1. The P prefix in a Freescale part number designates a “Pilot Production Prototype” as defined by Freescale SOP 3-13. These parts have only preliminary reliability and characterization data. Before pilot production prototypes can be shipped, written authorization from the customer must be on file in the applicable sales office acknowledging the qualification status and the fact that product changes may still occur as pilot production prototypes are shipped.

2 See Section 5.1, “DC Electrical Characteristics,” for information regarding V_{DD} specifications for 1400 MHz device.

4 General Parameters

Core power supply	1.3 V	(1700L MHz revision level D devices)
	1.15 V	(1400N MHz devices)
	1.1 V	(1267N MHz revision level C devices)
	1.05 V	(1267N MHz revision level D devices)
	1.0 V	(1000N MHz devices)

Note: See Section 5.1, “DC Electrical Characteristics,” for information regarding V_{DD} specifications for 1400 MHz device.

5.1 DC Electrical Characteristics

Table 4 provides the recommended operating conditions for the MPC7448 part numbers described here.

NOTE

Table 4 describes the nominal operating conditions of the device. For information on the operation of the device at supported derated core voltage conditions, see Section 5.3, “Voltage and Frequency Derating.”

Table 4. Recommended Operating Conditions[1]

Characteristic	Symbol	Recommended Value					Unit	Notes
		1000N MHz	1267N MHz[3] Revision Level C	1267N MHz[3] Revision Level D	1400N MHz[3]	1700L MHz		
Core supply voltage	V_{DD}	1.0 V ± 50 mV	1.1 V ± 50 mV	1.05 V ± 50 mV	1.15 V ± 50 mV	1.3 V +20/-50 mV	V	
PLL supply voltage	AV_{DD}	1.0 V ± 50 mV	1.1 V ± 50 mV	1.05 V ± 50 mV	1.15 V ± 50 mV	1.3 V +20/-50 mV	V	2
Die-junction temperature	T_j	–40 to 105	–40 to 105	–40 to 105	–40 to 105	–40 to 105	•C	

Notes:

1. These are the recommended and tested operating conditions. Some speed grades in addition support voltage derating; see Section 5.3, “Voltage and Frequency Derating.” Proper device operation outside of these conditions and those specified in Section 5.3, “Voltage and Frequency Derating,” is not guaranteed.
2. This voltage is the input to the filter discussed in Section 9.2.2, “PLL Power Supply Filtering,” in the hardware specifications and not necessarily the voltage at the AV_{DD} pin, which may be reduced from V_{DD} by the filter.
3. V_{DD} and AV_{DD} may be reduced in order to reduce power consumption if further maximum core frequency constraints are observed. See Section 5.3, “Voltage and Frequency Derating,” for specific information.

Table 7 provides the power consumption for the MPC7448 part numbers described by this document; see Section 11.1, “Part Numbers Addressed by This Specification,” for more information. The *MPC7448 RISC Microprocessor Hardware Specifications* presents guidelines on the use of these parameters for system design. For information on power consumption when dynamic frequency switching is enabled, see Section 9.8.5, “Dynamic Frequency Switching (DFS),” in the hardware specifications.

The power consumptions provided in Table 7 represent the power consumption of each speed grade when operated at the rated maximum core frequency (see Table 8). Freescale sorts devices by power as well as by core frequency, and power limits for each speed grade are independent of each other. Each device is tested at its maximum core frequency only. (Note that Deep Sleep Mode power consumption is independent of clock frequency.) Operating a device at a frequency lower than its rated maximum is fully supported provided the clock frequencies are within the specifications given in Table 8, and a device operated below its rated maximum will have lower power consumption. However, inferences should not be made about a device’s power consumption based on the power specifications of another (lower) speed grade. For example, a 1400 MHz device operated at 1267 MHz will not exhibit the same power consumption as a 1267 MHz device operated at 1267 MHz.

NOTE

The power consumption information in this table applies when the device operates at the nominal core voltage indicated in Table 4. For power consumption at derated core voltage conditions, see Section 5.3, “Voltage and Frequency Derating.”

Table 7. Power Consumption for MPC7448 at Maximum Rated Frequency

	Die Junction (T_j) (•C)	Maximum Processor Core Frequency (Speed Grade, MHz)				Unit	Notes
		1000N	1267N [7]	1400N	1700L		
Full-Power Mode							
Typical	65	9.5	8.4	11.0	21.0	W	1, 2
Thermal	105	12.0	10.3	13.7	25.6	W	1, 5
Maximum	105	13.9	12.0	15.9	29.8	W	1, 3
Nap Mode							
Typical	105	6.5	6.5	8.3	13.0	W	1, 6
Sleep Mode							
Typical	105	6.3	6.3	8.0	12.5	W	1, 6
Deep Sleep Mode (PLL Disabled)							
Typical	105	6.0	6.0	7.7	12.0	W	1, 6

Notes:

1. These values specify the power consumption for the core power supply (V_{DD}) at nominal voltage and apply to all valid processor bus frequencies and configurations. The values do not include I/O supply power (OV_{DD}) or PLL supply power (AV_{DD}). OV_{DD} power is system dependent but is typically < 5% of V_{DD} power. Worst case power consumption for AV_{DD} < 13 mW.
2. Typical nominal power consumption is an average value measured at the nominal recommended V_{DD} (see Table 4) and 65°C while running the Dhrystone 2.1 benchmark and achieving 2.3 Dhrystone MIPs/MHz. This parameter is not 100% tested but periodically sampled.
3. Maximum power consumption is the average measured at nominal V_{DD} and maximum operating junction temperature (see Table 4) while running an entirely cache-resident, contrived sequence of instructions to keep all the execution units maximally busy.
4. Doze mode is not a user-definable state; it is an intermediate state between full-power and either nap or sleep mode. As a result, power consumption for this mode is not tested.
5. Typical thermal power consumption is an average value measured at the nominal recommended V_{DD} (see Table 4) and 105°C while running the Dhrystone 2.1 benchmark and achieving 2.3 Dhrystone MIPs/MHz. This parameter is not 100% tested but periodically sampled.
6. Typical power consumption for these modes is measured at the nominal recommended V_{DD} (see Table 4) and 105°C in the mode described. This parameter is not 100% tested but is periodically sampled.
7. Power consumption for the 1267 MHz device is intentionally constrained via testing and sorting to assure low power consumption for this device.

5.2.1 Clock AC Specifications

Table 8 provides the clock AC timing specifications for the MPC7448 part numbers discussed here.

NOTE

The core frequency information in this table applies when the device operates at the nominal core voltage indicated in Table 4. For core frequency specifications at derated core voltage conditions, see Section 5.3, “Voltage and Frequency Derating.”

Table 8. Clock AC Timing Specifications

At recommended operating conditions. See Table 4.

Characteristic	Symbol	Maximum Processor Core Frequency (MHz)								Unit	Notes
		1000N		1267N		1400N		1700L			
		Min	Max	Min	Max	Min	Max	Min	Max		
Processor frequency DFS mode disabled	f_{core}	500	1000	500	1267	500	1400	600	1700	MHz	1, 8, 9
Processor frequency DFS mode enabled	f_{core_DFS}	250	500	250	633	250	700	300	850	MHz	10
VCO frequency	f_{VCO}	500	1000	500	1267	500	1400	600	1700	MHz	1, 9

Notes:

1. **Caution**: The SYSCLK frequency and PLL_CFG[0:5] settings must be chosen such that the resulting SYSCLK (bus) frequency, processor core frequency, and PLL (VCO) frequency do not exceed their respective maximum or minimum operating frequencies. Refer to the PLL_CFG[0:5] signal description in Section 9.1.1, “PLL Configuration,” in the hardware specifications for valid PLL_CFG[0:5] settings.
8. This reflects the maximum and minimum core frequencies when the dynamic frequency switching feature (DFS) is disabled. f_{core_DFS} provides the maximum and minimum core frequencies in a DFS mode.
9. **Caution**: These values specify the maximum processor core and VCO frequencies when the device is operated at the nominal core voltage. If operating the device at the derated core voltage, the processor core and VCO frequencies must be reduced. See Section 5.3, “Voltage and Frequency Derating,” for more information.
10. This specification supports the Dynamic Frequency Switching (DFS) feature and is applicable only when one of the DFS modes (divide-by-2 or divide-by-4) is enabled. When DFS is disabled, the core frequency must conform to the maximum and minimum frequencies stated for f_{core}.

5.3 Voltage and Frequency Derating

To reduce power consumption, these devices support voltage and frequency derating in which the core voltage (V_{DD}) may be reduced if the reduced maximum processor core frequency requirements are observed. The supported derated core voltage, resulting maximum processor core frequency (f_{core}), and power consumption are provided in Table 11. Only those parameters in Table 11 are affected; all other parameter specifications are unaffected.

Table 11. Supported Voltage, Core Frequency, and Power Consumption Derating

Maximum Rated Core Frequency (Device Marking)	Supported Derated Core Voltage (V_{DD})	Maximum Derated Core Frequency (f_{core})	Full-Power Mode Power Consumption		
			Typical	Thermal	Maximum
1000N	N/A				
1267N	1.0 V ± 50 mV	1000 MHz	6.0 W	7.3 W	8.5 W
1400N	1.0 V ± 50 mV	1000 MHz	8.0 W	9.9 W	11.5 W
1700L	N/A				

9.2 Power Supply Design and Sequencing

The power supply design and sequencing requirements of the devices described here are identical to those described in the *MPC7448 RISC Microprocessor Hardware Specifications*.

11 Part Numbering and Marking

11.1 Part Numbers Addressed by This Specification

Table 17 provides the ordering information for the MPC7448 parts described in this document.

Table 17. Part Marking Nomenclature

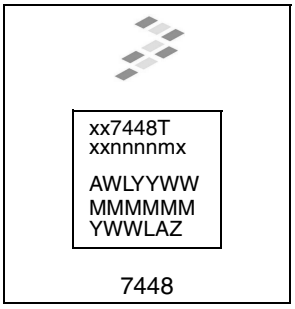
xx	**7448**	**T**	***xx***	***nnnn***	**m**	***x***
Product Code	**Part Identifier**	**Specification Modifier**	**Package**	**Processor Frequency**	**Application Modifier**	**Revision Level**
MC PPC[1]	7448	T = Extended Temperature Device	HX = HCTE BGA	1000	N: 1.0 V ± 50 mV – 40 to 105 °C	C: 2.1: PVR = 0x8004_0201 D: 2.2: PVR = 0x8004_0202
				1267 Revision C only	N: 1.1 V ± 50 mV – 40 to 105 °C	
				1267 Revision D only	N: 1.05 V ± 50 mV – 40 to 105 °C	
				1400	N: 1.15 V ± 50 mV – 40 to 105 °C	
MC				1700	L: 1.3 V +20/-50 mV – 40 to 105 °C	D:2.2: PVR = 0x8004_0202

Notes:

1. The P prefix in a Freescale part number designates a “Pilot Production Prototype” as defined by Freescale SOP 3-13. These parts have only preliminary reliability and characterization data. Before pilot production prototypes can be shipped, written authorization from the customer must be on file in the applicable sales office acknowledging the qualification status and the fact that product changes may still occur as pilot production prototypes are shipped.

11.3 Part Marking

Parts are marked as the example shown in Figure 23.



Notes:
AWLYYWW is the test code, where YYWW is the date code (YY = year, WW = work week)
MMMMMM is the M00 (mask) number.
YWWLAZ is the assembly traceability code.

Figure 23. Part Marking for BGA Device

Document Revision History

Table B provides a revision history for this part number specification.

Table B. Document Revision History

Revision	Date	Substantive Change(s)
2	04/2007	Added 1700LD device information. On first page changed title part number from being N application modifier specific (MC7448TxxxnnnnNx) to generic MC7448Txxnnnnmx. On first page under Freescale Part Numbers Affected added MC7448THX1700LD. Table A: Added a 1700L MHz revision D row. Section 4, “General Parameters”: Added 1700L MHz revision level D information and added N application modifier information to the 1000, 1267, and 1400 devices. Table 4, Table 7, and Table 8: Added 1700L columns. Table 4, Table 7, Table 8, and Table 11: Added added N application modifier information to the 1000, 1267, and 1400 column headings. Table 11: Added 1700L row. Table 17: Changed ‘N’ application modifier at top of table to generic ‘m’. Added 1700L information for revision level D. Figure 23: Updated part marking replacing ‘N’ application modifier with ‘m’.
1	10/2006	Added revision level D device information. On first page under Freescale Part Numbers Affected added PPC7448THX1000Nx, PPC7448THX1267Nx, and PPC7448THX1400Nx. Table A and list on first page: x stands for C or D revision level. Table A: Added 1267 MHz revision D row and 4 PPC part number rows. Section 4, “General Parameters”: Added 1267 MHz revision level D information. Table 4: Added 1267 MHz revision D only column. Table 17: Added PVR and 1267 information for revision level D, added PPC product code, and footnote 1.
0	6/2006	Initial release.

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